



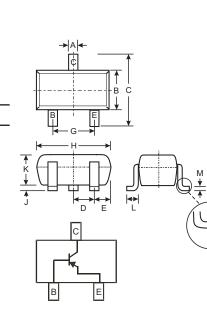
PNP SMALL SIGNAL SURFACE MOUNT TRANSISTOR

Features

- Epitaxial Planar Die Construction
- Complementary NPN Type Available (MMST4401)
- Ultra-Small Surface Mount Package
- Lead Free/RoHS Compliant (Note 2)
- "Green" Device (Note 3 and 4)

Mechanical Data

- Case: SOT-323
- Case Material: Molded Plastic, "Green" Molding Compound, Note 4. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Solderable per MIL-STD-202, Method 208
- Terminal Connections: See Diagram
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe).
- Marking (See Page 2): K3T
- Ordering & Date Code Information: See Page 2
- Weight: 0.006 grams (approximate)



SOT-323						
Dim	Min	Мах				
Α	0.25	0.40				
В	1.15	1.35				
С	2.00	2.20				
D	0.65 N	ominal				
Е	0.30	0.40				
G	1.20	1.40				
Н	1.80 2.20					
J	0.0	0.10				
к	0.90 1.00					
L	0.25	0.40				
М	0.10	0.18				
α	0°	8 °				
All Dimensions in mm						

Maximum Ratings @ $T_A = 25^{\circ}C$ unless otherwise specified

Characteristic	Symbol	MMST4403	Unit		
Collector-Base Voltage	V _{CBO}	-40	V		
Collector-Emitter Voltage	V _{CEO}	-40	V		
Emitter-Base Voltage	V _{EBO}	-5.0	V		
Collector Current - Continuous (Note 1)	Ι _C	-600	mA		
Power Dissipation (Note 1)	Pd	200	mW		
Thermal Resistance, Junction to Ambient (Note 1)	R _{0JA}	625	K/W		
Operating and Storage and Temperature Range	Tj, T _{STG}	-55 to +150	°C		

Note: 1. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout

document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.

2. No purposefully added lead.

3. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com./products/lead_free/index.php.

4. Product manufactured with Date Code 0609 (week 9, 2006) and newer are built with Green Molding Compound. Product manufactured prior to Date Code 0609 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.



Characteristic		Min	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 5)						
Collector-Base Breakdown Voltage	V _{(BR)CBO}	-40	_	V	$I_{C} = -100 \mu A, I_{E} = 0$	
Collector-Emitter Breakdown Voltage	V _{(BR)CEO}	-40		V	$I_{\rm C} = -1.0 {\rm mA}, I_{\rm B} = 0$	
Emitter-Base Breakdown Voltage	V _{(BR)EBO}	-5.0		V	$I_{E} = -100 \mu A, I_{C} = 0$	
Collector Cutoff Current	I _{CEX}		-100	nA	$V_{CE} = -35V, V_{EB(OFF)} = -0.4V$	
Base Cutoff Current	I _{BL}		-100	nA	$V_{CE} = -35V, V_{EB(OFF)} = -0.4V$	
ON CHARACTERISTICS (Note 5)						
DC Current Gain	h _{FE}	30 60 100 100 20	 		$\begin{array}{ccc} I_C = & -100 \mu A, V_{CE} = & -1.0V \\ I_C = & -1.0mA, V_{CE} = & -1.0V \\ I_C = & -10mA, V_{CE} = & -1.0V \\ I_C = & -150mA, V_{CE} = & -2.0V \\ I_C = & -500mA, V_{CE} = & -2.0V \end{array}$	
Collector-Emitter Saturation Voltage	V _{CE(SAT)}		-0.40 -0.75	V	$I_{C} = -150$ mA, $I_{B} = -15$ mA $I_{C} = -500$ mA, $I_{B} = -50$ mA	
Base-Emitter Saturation Voltage	V _{BE(SAT)}	-0.75	-0.95 -1.30	V	$I_{C} = -150mA$, $I_{B} = -15mA$ $I_{C} = -500mA$, $I_{B} = -50mA$	
SMALL SIGNAL CHARACTERISTICS						
Output Capacitance	C _{cb}		8.5	pF	$V_{CB} = -10V, f = 1.0MHz, I_E = 0$	
Input Capacitance	C _{eb}	_	30	pF	$V_{EB} = -0.5V, f = 1.0MHz, I_C = 0$	
Input Impedance	h _{ie}	1.5	15	kΩ		
Voltage Feedback Ratio	h _{re}	0.1	8.0	x 10 ⁻⁴	$V_{CE} = -10V, I_{C} = -1.0mA,$	
Small Signal Current Gain	h _{fe}	60	500	_	f = 1.0kHz	
Output Admittance	h _{oe}	1.0	100	μS		
Current Gain-Bandwidth Product	fT	200	_	MHz	$V_{CE} = -10V, I_C = -20mA, f = 100MHz$	
SWITCHING CHARACTERISTICS						
Delay Time	t _d	—	15	ns	$V_{CC} = -30V, I_C = -150mA,$	
Rise Time	tr	—	20	ns	$V_{BE(off)} = -2.0V, I_{B1} = -15mA$	
Storage Time	ts	_	225	ns	V _{CC} = -30V, I _C = -150mA,	
Fall Time	tf	_	30	ns	$I_{B1} = I_{B2} = -15 \text{mA}$	

Electrical Characteristics @ T_A = 25°C unless otherwise specified

Ordering Information (Note 4 & 6)

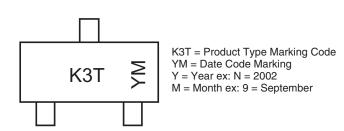
Device	Packaging	Shipping			
MMST4403-7-F	SOT-323	3000/Tape & Reel			

Notes: 4. Product manufactured with Date Code 0609 (week 9, 2006) and newer are built with Green Molding Compound. Product manufactured prior to Date Code 0609 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.

5. Short duration test pulse used to minimize self-heating effect.

6. For Packaging Details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

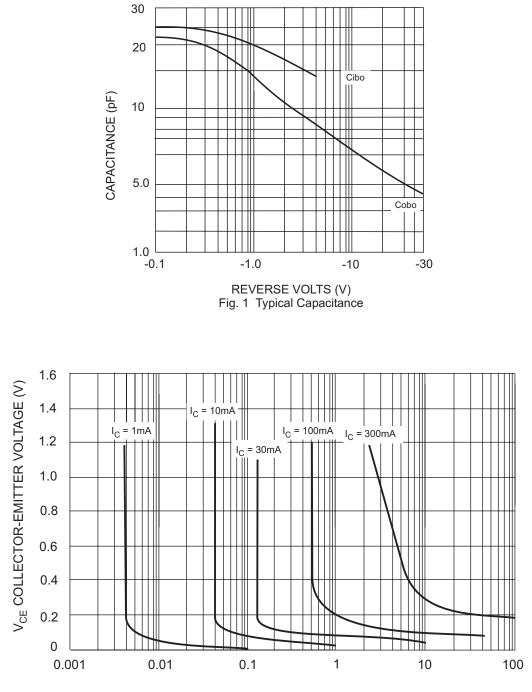
Marking Information



Date Code Key

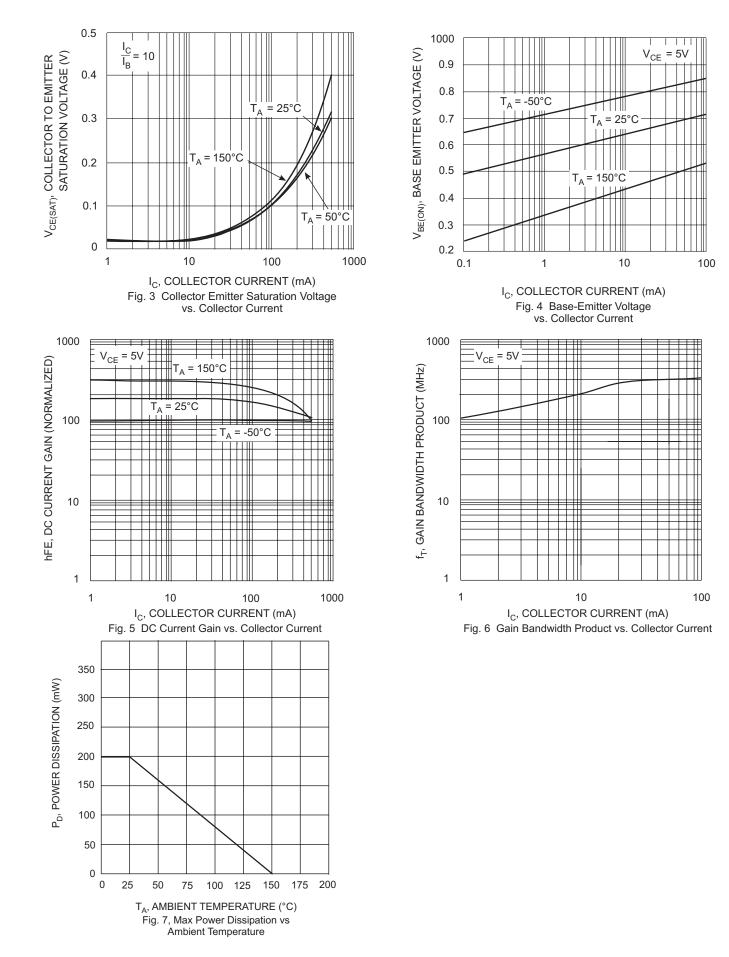
Year	1998	1999	2000	2001	2002	2003	2004	2005	2006	2007	2008	2009
Code	J	К	L	М	Ν	Р	R	S	Т	U	V	W
Month	Jan	Feb	March	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D





I_B BASE CURRENT (mA) Fig. 2 Typical Collector Saturation Region







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